

45P80-1

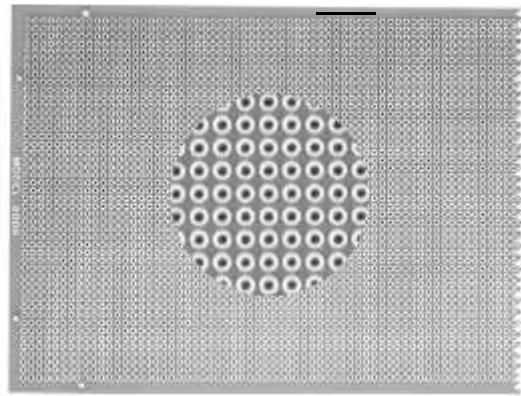
Circuit Pattern:

Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Solder Terminals:
Wire-Wrap Socket Pins:
Hole Diameter:

4.5" x 8.08"

Pad-Per-Hole
2 sides
N/A
8.08"/.062"
4.50"
80
CEM-1
T44, T46, T49, T68
T42-1
R32
.042"

- 0.100" grid
- Top/Bottom rows on .200 pitch with no plating
- Isolated .085" square pads around each hole
- Plated thru holes and ground plane identical both sides



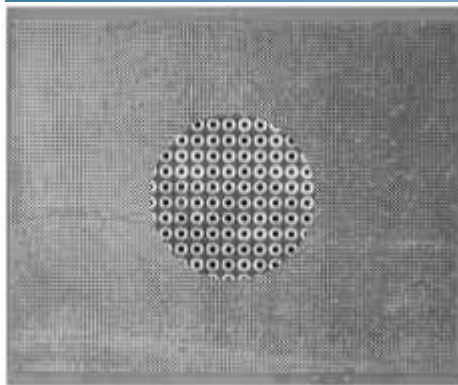
8006

Circuit Pattern:
Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Solder Terminals:
Wire-Wrap Socket Pins:
Hole Diameter:

5.0" x 13.25"

Pad-Per-Hole
N/A
13.25"/.062"
5.00"
154
FR4 Epoxy Glass
T44, T46, T49, T68
T42-1
R32
.042"

- 0.100" grid
- Copper plated-thru holes both sides
- 0.080" diameter, isolated solder pad around each hole, both sides
- Unrestricted component placement, extended area for high density applications
- Board can be cut down into smaller units



8012

Circuit Pattern:
Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Solder Terminals:
Wire-Wrap Socket Pins:
Hole Diameter:

9.2" x 11.0"

Pad-Per-Hole
N/A
11.00"/.062"
9.20"
283
FR4 Epoxy Glass
T44, T46, T49, T68
T42-1
R32
.042"

- 0.100" grid
- Plated-thru holes
- 0.080" diameter, isolated solder pad around each hole, both sides
- Approximates Eurocard (DIN) specifications: 6U x 280mm, can be sheared down to 6U x 220mm or 160mm
- Unrestricted component placement, extended area for high density applications

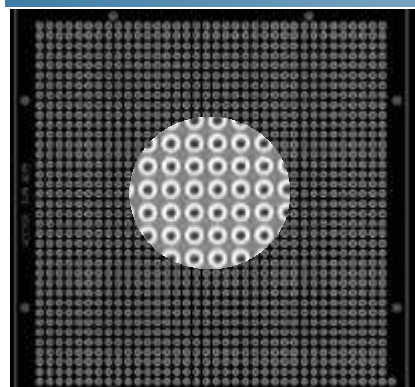
8013

Circuit Pattern:
Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Solder Terminals:
Wire-Wrap Socket Pins:
Hole Diameter:

10.6" x 18.0"

Pad-Per-Hole
N/A
6.00"/.062"
18.0"
165
FR4 Epoxy Glass
T44, T46, T49, T68
T42, K24C
R32
.042"

- 0.100" grid
- Isolated round pads around each hole
- Plated-thru holes
- 0.080" diameter, isolated solder pad around each hole, both sides
- Unrestricted component placement, extended area for high density applications



8015 (2 sided pattern)

8015-1 (1 sided pattern-plated holes)

Circuit Pattern:
Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Solder Terminals:
Wire-Wrap Socket Pins:
Hole Diameter:

Pad-Per-Hole,
N/A
4.00"/.062"
6.00"
72
FR4
T44, T46, T49, T68
T42-1, K24C
R32
.042"

4.0" x 6.0"

4.0" x 4.0"

- 0.100" grid
- Isolated round pads around each hole (8015-1)
- Plated-thru holes
- 0.080" diameter, isolated solder pad around each hole, both sides
- Unrestricted component placement, extended area for high density applications